introducing an optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a semiconductor laser light onto said optical disk through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is 30/mm^2 or less;

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

15. (Thrice Amended) A method for operating an optically recordable disk memory comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a semiconductor laser light onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is 30/mm^2 or less, and wherein said hard-carbon coating is an outermost layer of the disk.

22. (Thrice Amended) A method for operating an optically recordable disk memory comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a semiconductor laser light onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is 30/mm^2 or less;

wherein said contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

29. (Thrice Amended) A method for operating an optically recordable disk memory comprising the steps of:

introducing an optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a laser light having an wavelength of 700 to 800 nm onto said optical disk through said hard-carbon coating ;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less, and wherein said hard-carbon coating is an outermost layer of the disk.

36. (Thrice Amended) A method for operating an optically recordable disk memory comprising the steps of:

introducing an optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a laser light having an wave length of 700 to 800 nm onto said optical disk through said hard-carbon coating ;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less;

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

43. (Thrice Amended) A method for operating an optically recordable disk memory comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a laser light having an wave length of 700 to 800 nm onto said substrate through said hard-carbon coating ;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less, and wherein said hard-carbon coating is an outermost layer of the disk.

SUB f8

50. (Thrice Amended) A method for operating an optically recordable disk memory comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

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irradiating a laser light having an wave length of 700 to 800 nm onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less;

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

SUB f9

57. (Thrice Amended) A method for operating an optically recordable disk memory comprising the steps of:

introducing an optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

f9

irradiating a visible light onto said optical disk through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less, and wherein said hard-carbon coating is an outermost layer of the disk.

58. (Thrice Amended) A method for operating an optically recordable disk memory comprising the steps of:

introducing an optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a visible light onto said optical disk through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less;

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

59. (Thrice Amended) A method for operating an optically recordable disk memory comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a visible light onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less, and wherein said hard-carbon coating is an outermost layer of the disk.

60. (Thrice Amended) A method for operating an optically recordable disk memory comprising the steps of:

K9 cont.

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a visible light onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less;

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

SUB f10

68. (Amended) A method of operating an optical magnetic disk comprising the steps of:

introducing an optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a semiconductor laser light onto said optical disk through said hard-carbon coating;

K10

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less, and wherein said hard-carbon coating is an outermost layer of the disk.

69. (Amended) A method of operating an optical magnetic disk comprising the steps of:

introducing an optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a semiconductor laser light onto said optical disk through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is 30/mm^2 or less,

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

70. (Amended) A method of operating an optical magnetic disk comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a semiconductor laser light onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is 30/mm^2 or less, and wherein said hard-carbon coating is an outermost layer of the disk.

E10 cont.

71. (Amended) A method of operating an optical magnetic disk comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a semiconductor laser light onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is 30/mm^2 or less;

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

SUB F11

79. (Amended) A method of operating an optical magnetic disk comprising the steps of:

introducing an optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

E11

irradiating a laser light having an wave length of 700 to 800 nm onto said optical disk through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less.

80. (Amended) A method of operating an optical magnetic disk comprising the steps of:

introducing an optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a laser light having an wave length of 700 to 800 nm onto said optical disk through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less,

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

81. (Amended) A method of operating an optical magnetic disk comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a laser light having an wave length of 700 to 800 nm onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less, and wherein said hard-carbon coating is an outermost layer of the disk.

82. (Amended) A method of operating an optical magnetic disk comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a laser light having an wave length of 700 to 800 nm onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less;

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

90. (Amended) A method of operating an optical magnetic disk comprising the steps of:

introducing an optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a visible light onto said optical disk through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less, and wherein said hard-carbon coating is an outermost layer of the disk.

91. (Amended) A method of operating an optical magnetic disk comprising the steps of:

introducing an optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a visible light onto said optical disk through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less,

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

92. (Amended) A method of operating an optical magnetic disk comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a visible light onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less, and wherein said hard-carbon coating is an outermost layer of the disk.

93. (Amended) A method of operating an optical magnetic disk comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a visible light onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is 30/mm^2 or less;

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

101. (Amended) A method of operating a compact disk comprising the steps of:

introducing an optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a semiconductor laser light onto said optical disk through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is 30/mm^2 or less, and wherein said hard-carbon coating is an outermost layer of the disk.

102. (Amended) A method of operating a compact disk comprising the steps of:

introducing an optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a semiconductor laser light onto said optical disk through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is 30/mm^2 or less,

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

103. (Amended) A method of operating a compact disk comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a semiconductor laser light onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is 30/mm^2 or less, and wherein said hard-carbon coating is an outermost layer of the disk.

104. (Amended) A method of operating a compact disk comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a semiconductor laser light onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is 30/mm^2 or less;

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

112. (Amended) A method of operating a compact disk comprising the steps of:

introducing an optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a laser light having an wave length of 700 to 800 nm onto said optical disk through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is 30/mm^2 or less, and wherein said hard-carbon coating is an outermost layer of the disk.

113. (Amended) A method of operating a compact disk comprising the steps of:

introducing an optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a laser light having an wave length of 700 to 800 nm onto said optical disk through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is 30/mm^2 or less,

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

114. (Amended) A method of operating a compact disk comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a laser light having an wave length of 700 to 800 nm onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less, and wherein said hard-carbon coating is an outermost layer of the disk.

E15 cont

115. (Amended) A method of operating a compact disk comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a laser light having an wave length of 700 to 800 nm onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less;

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

SUB E15

123. (Twice Amended) A method of operating a compact disk comprising the steps of:

introducing an optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a visible light onto said optical disk through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less, and wherein said hard-carbon coating is an outermost layer of the disk.

E16

124. (Amended) A method of operating a compact disk comprising the steps of:

introducing an optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a visible light onto said optical disk through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is 30/mm^2 or less,

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

125. (Amended) A method of operating a compact disk comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a visible light onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is 30/mm^2 or less, and wherein said hard-carbon coating is an outermost layer of the disk.

E16 cont.

126. (Amended) A method of operating a compact disk comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a visible light onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is 30/mm^2 or less;

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

SUB file

134. (Amended) A method of operating an optical disk comprising the steps of:

introducing said optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

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irradiating a semiconductor laser light onto said optical disk through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is 30/mm^2 or less.

135. (Amended) A method of operating an optical disk comprising the steps of:

introducing said optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a semiconductor laser light onto said optical disk through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less,

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

136. (Amended) A method of operating an optical disk comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a semiconductor laser light onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less, and wherein said hard-carbon coating is an outermost layer of the disk.

137. (Amended) A method of operating an optical disk comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a semiconductor laser light onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less;

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

145. (Amended) A method of operating an optical disk comprising the steps of:

introducing said optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a laser light having an wave length of 700 to 800 nm onto said optical disk through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less, and wherein said hard-carbon coating is an outermost layer of the disk.

146. (Amended) A method of operating an optical disk comprising the steps of:

introducing said optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a laser light having an wave length of 700 to 800 nm onto said optical disk through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less,

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

E18 cont.

147. (Amended) A method of operating an optical disk comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a laser light having an wave length of 700 to 800 nm onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is $30/mm^2$ or less, and wherein said hard-carbon coating is an outermost layer of the disk.

148. (Amended) A method of operating an optical disk comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a laser light having an wave length of 700 to 800 nm onto said substrate through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is 30/mm^2 or less;

E18 cont wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

Sub E18 156. (Amended) A method of operating an optical disk comprising the steps of:

introducing said optical disk having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a visible light onto said optical disk through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is 30/mm^2 or less, and wherein said hard-carbon coating is an outermost layer of the disk.

157. (Amended) A method of operating an optical disk comprising the steps of:

introducing said optical disk having a surface protected by a protective film comprising

E19 a hard-carbon coating having a thickness of 500Å or less;

irradiating a visible light onto said optical disk through said hard-carbon coating;

wherein the number of pin-holes in said hard-carbon coating is 30/mm^2 or less,

wherein said hard-carbon coating contains at least one of element selected from the group consisting of Si, B, N, P and F, and wherein said hard-carbon coating is an outermost layer of the disk.

158. (Amended) A method of operating an optical disk comprising the steps of:

introducing a substrate made of an organic resin or an industrial plastic material, said substrate having a surface protected by a protective film comprising a hard-carbon coating having a thickness of 500Å or less;

irradiating a visible light onto said substrate through said hard-carbon coating;